IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhtp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier	Information													
Company name*				mpany unique ID			Unique ID Authority				Response Date*			
nsemi											2025-08-01			
Contact Na	me	Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-Ei	nv-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			F	Phone - Representative*				Email - Representative*				
Product-E	nv-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Version Manufacturing Site		V	Weight*	UOM	Unit Type
	US2AA HER SMA		HER SMA GPPN 1	ER SMA GPPN 1.5A 50V		2025-08-01		Т	TSCBE		64.016	mg	Each	
	turing Process Inform		Comminal Desay	Allow	STD 020 MSI	Dating	Dools Pro-	aga Dody T		May Time at Perla	Townsort	Mary L	or of Deflow C	alac
<u> </u>		,		STD-020 MSL	Kating	Peak Process Body Tem		•				er of Reflow Cyc	cies	
•	Matte Tin (Sn) - annealed	C	CU Alloy	l			260		l C	30	secono	ds 3		
omments				10 1										
	ximum time at peak tempera													
or more in	iformation regarding materia	al composition	please refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warrant											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.28	mg	A	Lead (Pb)	7439-92-1	7c	0.0614	mg
			Supplier	Silicon (Si)	7440-21-3		1.2006	mg
			В	Nickel (Ni)	7440-02-0		0.0115	mg
			Supplier	Gold (Au)	7440-57-5		0.0064	mg
Die Attach Solder	2.098	mg	Supplier	Silver (Ag)	7440-22-4		0.0525	mg
			A	Lead (Pb)	7439-92-1	7a	1.9407	mg
			Supplier	Tin (Sn)	7440-31-5		0.1049	mg
Lead Frame	18.636	mg	Supplier	Iron (Fe)	7439-89-6		0.024	mg
			Supplier	Copper (Cu)	7440-50-8		18.6	mg
			Supplier	Phosphorus (P)	7723-14-0		0.012	mg
Mold Compound-Black	41.002	mg		Metal Hydroxide	proprietary data		3.0752	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.1503	mg
			Supplier	Carbon Black (C)	1333-86-4		0.205	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.2914	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.2802	mg
Plating	1.0	mg	Supplier	Tin (Sn)	7440-31-5		1	mg